

*NASA-ESA Product Data Exchange Workshop
Kent Space Center, 29 April - 1 May 2009*

NX PCB.xchange ECAD / MCAD / CAE Collaboration



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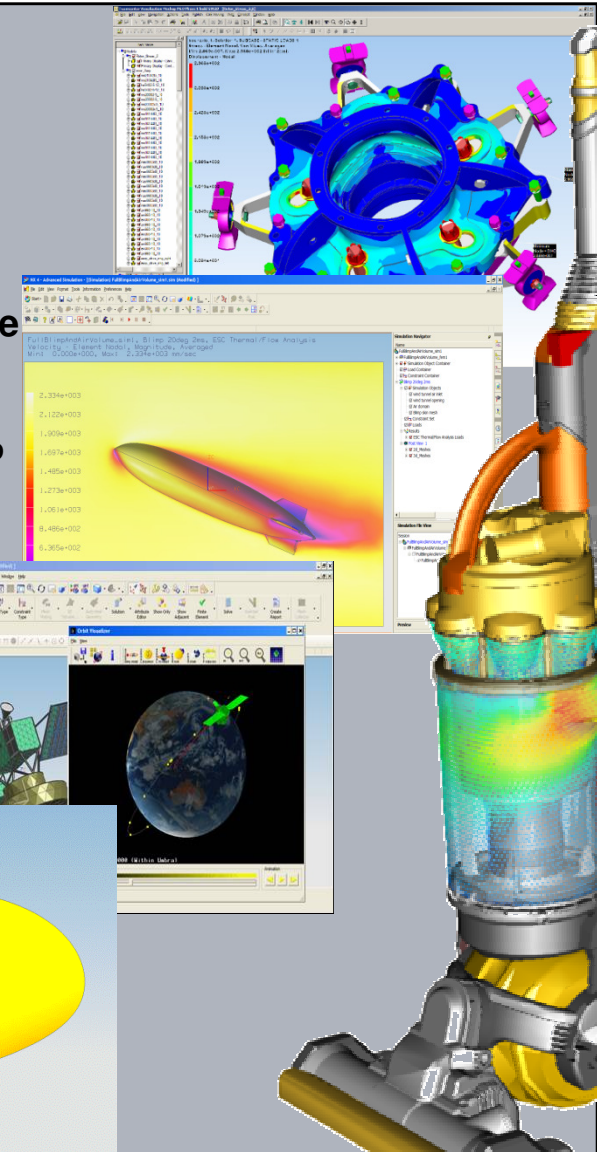
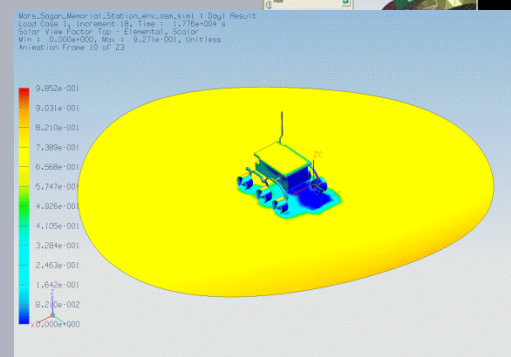
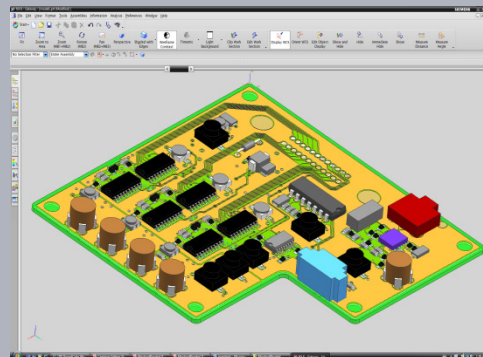
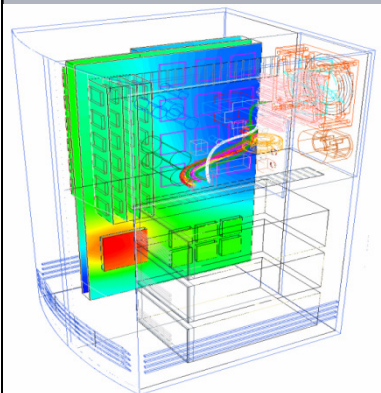
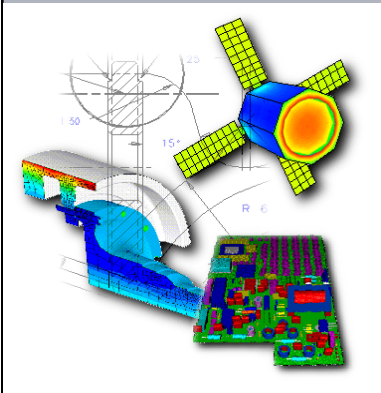
Maya Heat Transfer Technologies Ltd.



❑ Leading supplier of advanced thermal, fluid flow and structural analysis software.

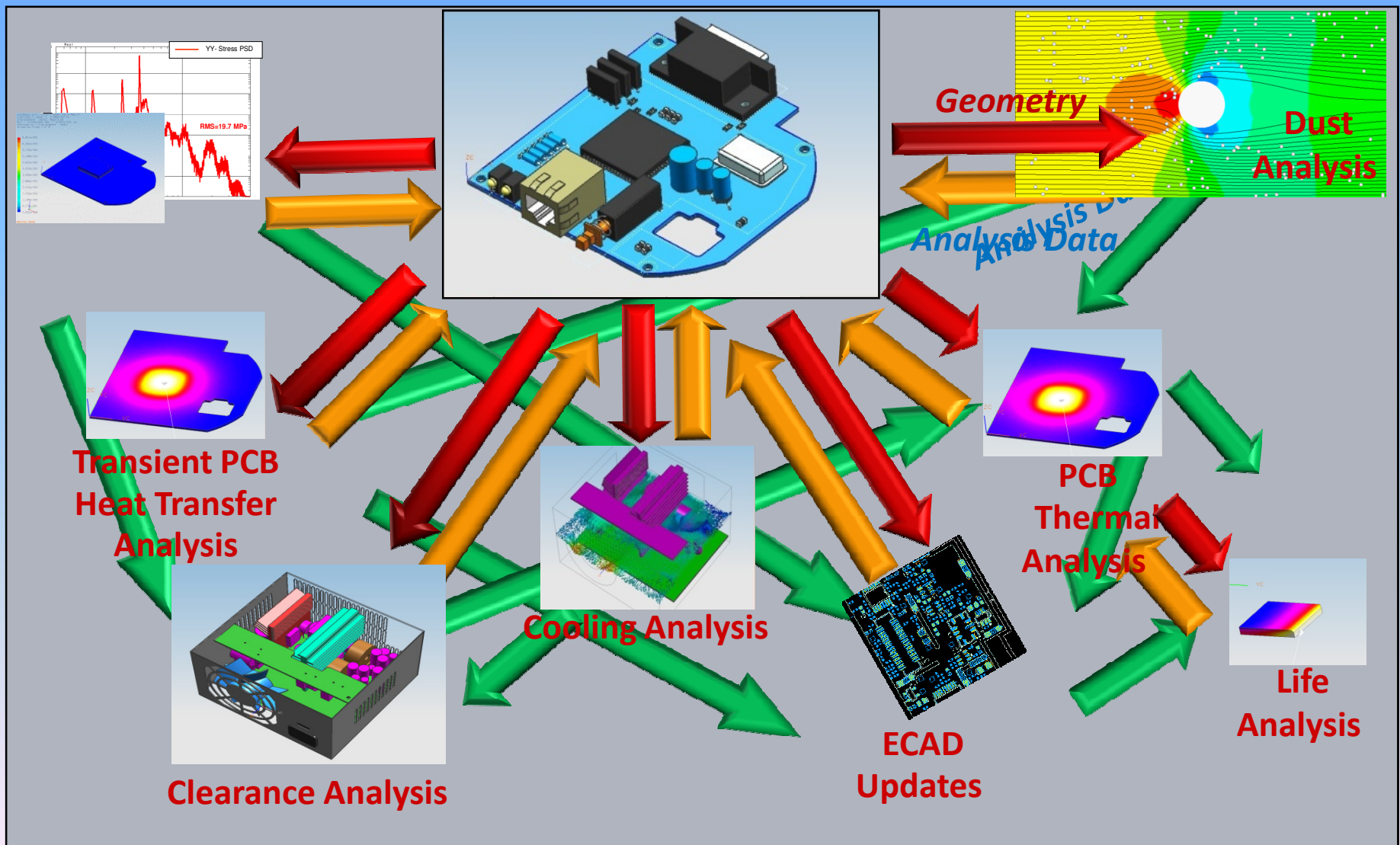
❑ Long-term partnership with Siemens PLM Software

❑ Our products are fully integrated in I-deas, FEMAP and NX



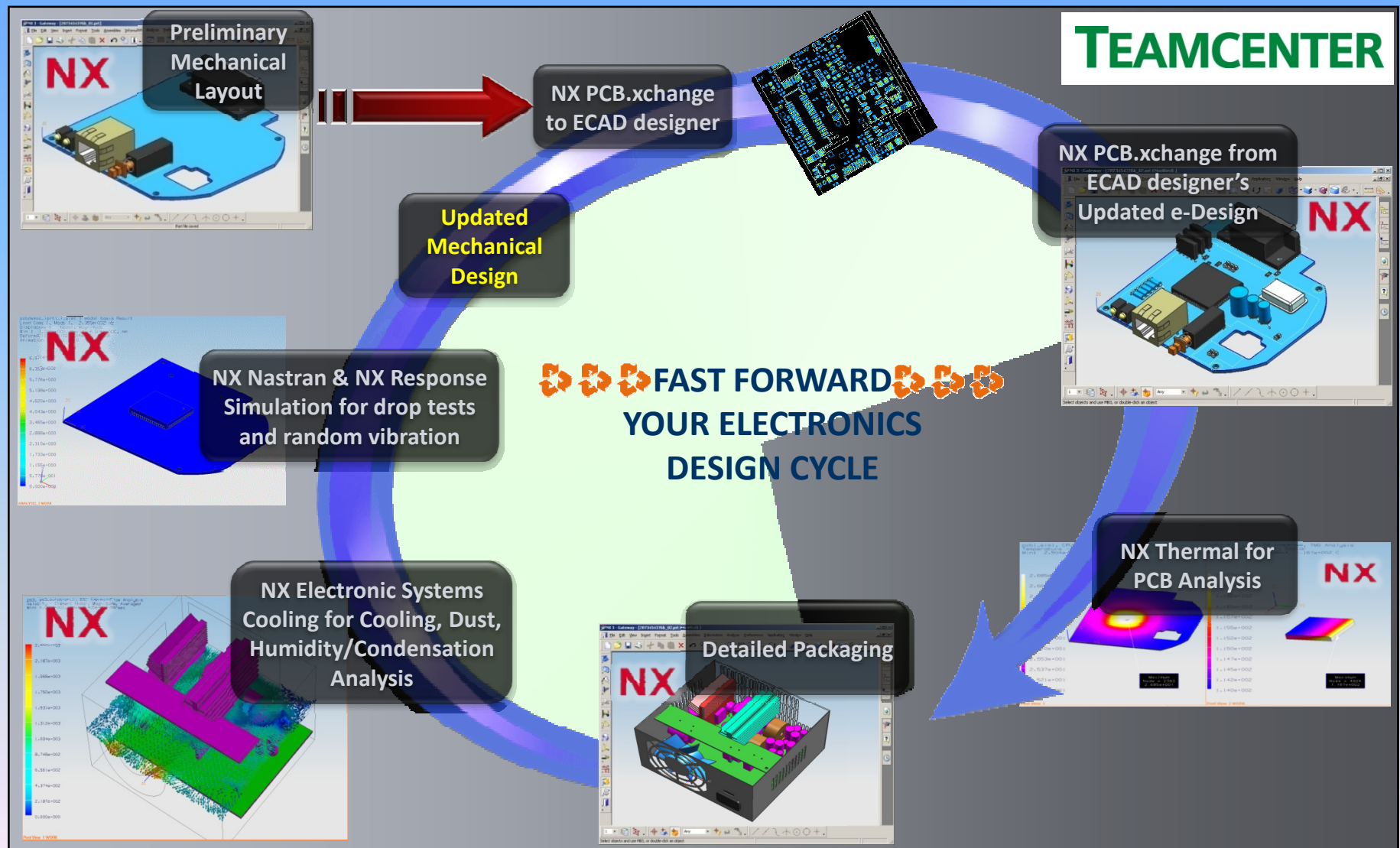
Most Electronic Systems Design Environment Today...

The long and tedious way...

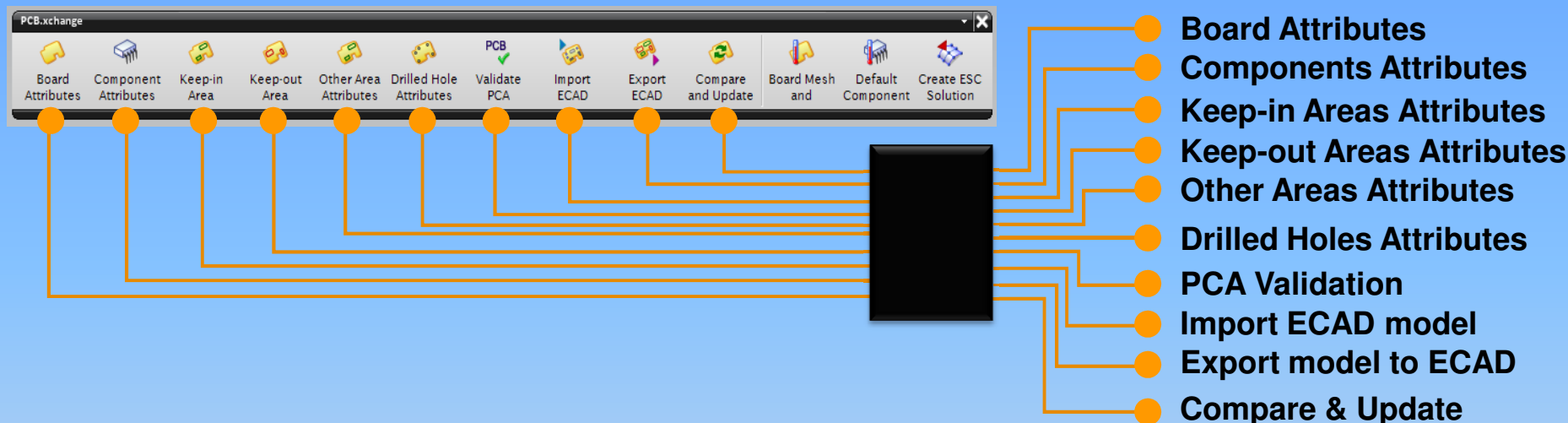


Our Vision...

Best-in-class Electronic Systems Mechanical Design/Analysis Environment
Complete & Managed ECAD/MCAD/CAE Workflows for PCBs & FPCs



PCB.xchange



➤ Toolset for NX Users to Collaborate with ECAD Users

- ✓ Eliminates Tedious Manual Work and Related Modeling Errors
- ✓ Enables a Much Faster Iterative Design Turnaround Time

➤ NX PCB.xchange Features a Unique “Compare & Update” Collaboration Capability

At each iteration:

- ✓ Identify/select changes you want to update from ECAD to NX
- ✓ Auto-create comparison report of ECAD/NX BOM between versions

PCB.xchange

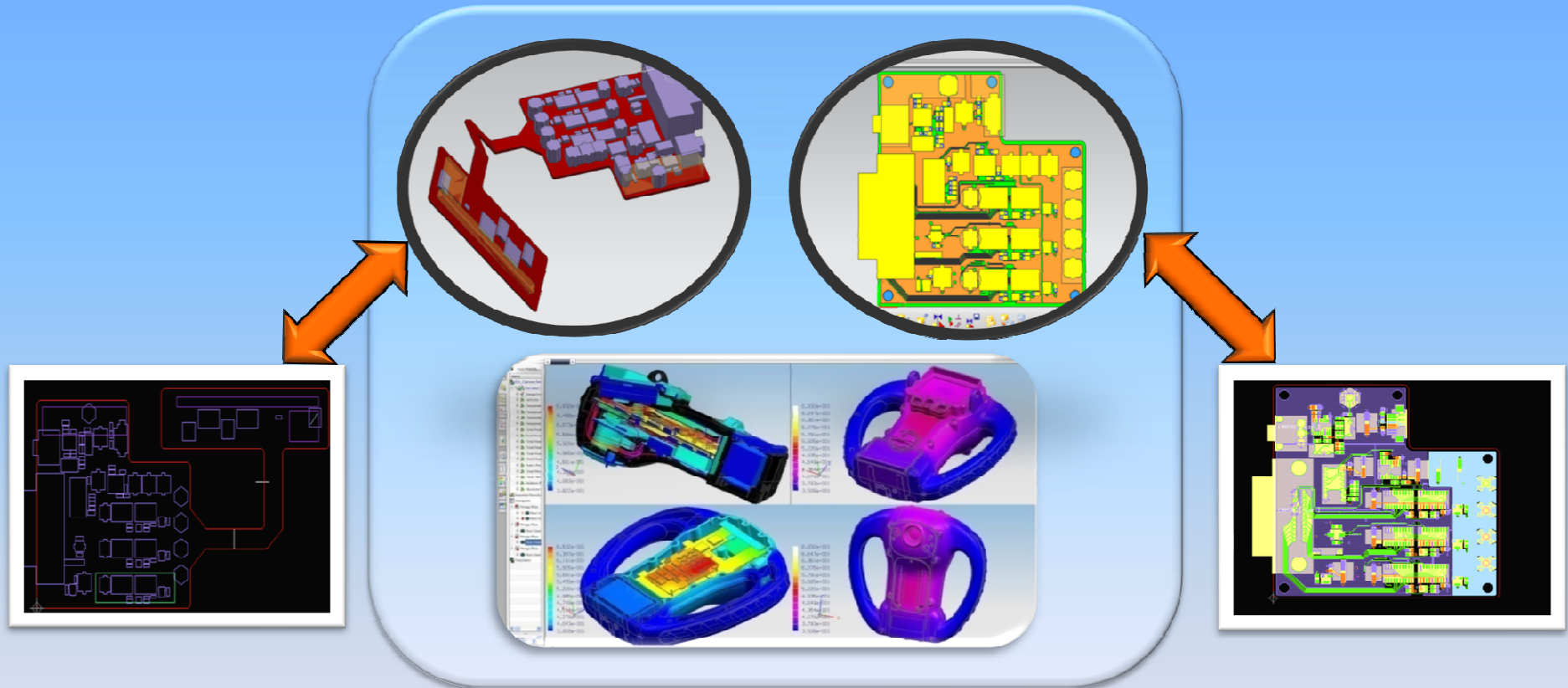
Questions asked at the 9th PDE workshop (2 years ago):

- Solutions for the new user requirements ?
- Overcome limitations of IDF “Intermediate Data Format” versions 2 & 3 ?

New requirements

- ❖ Exchanging more electrical data: traces, pads, etc
- ❖ Exchanging more mechanical data: Flex PC bend info, support multi-extrusions with different thicknesses, etc
- ❖ Exchanging more CAE data: material, thermo-optical data, heat loads, thermal resistances, etc
- Other format !?

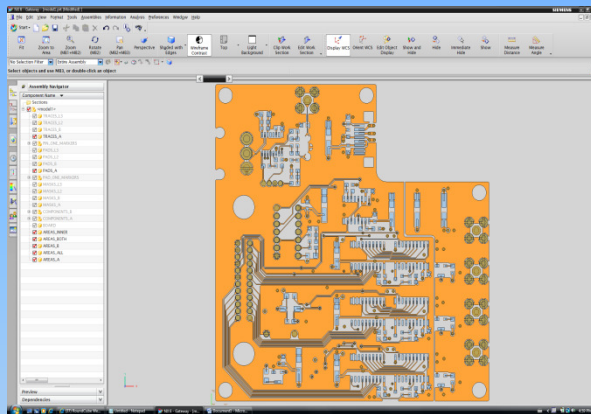
PCB.xchange



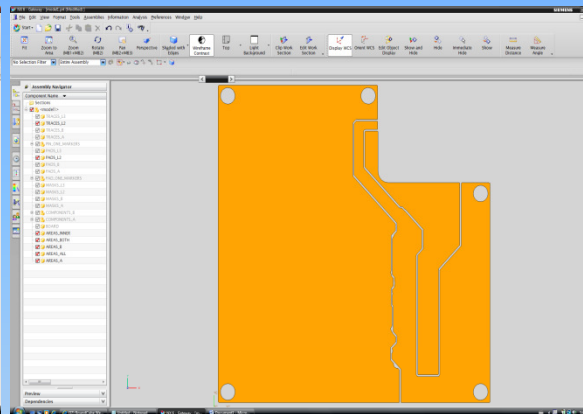
- More Electrical / Mechanical / Analysis Data supported
- Modeling and Exchanging Rigid and Flexible PCs
- Better Collaboration

More Electrical Data

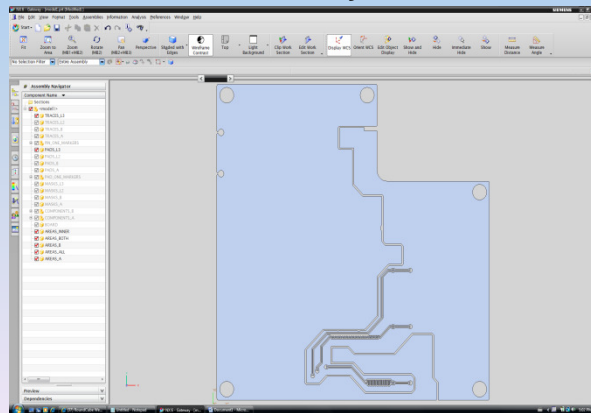
Top Layer



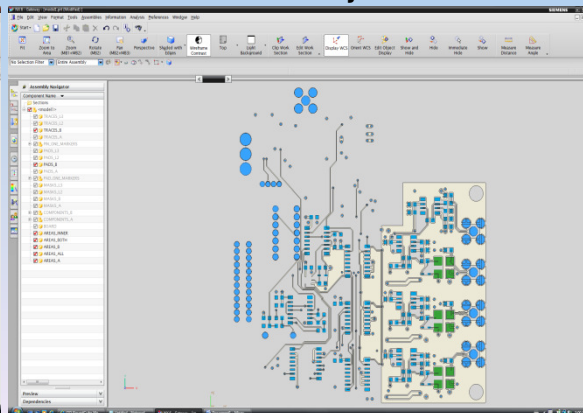
Internal Layer 1



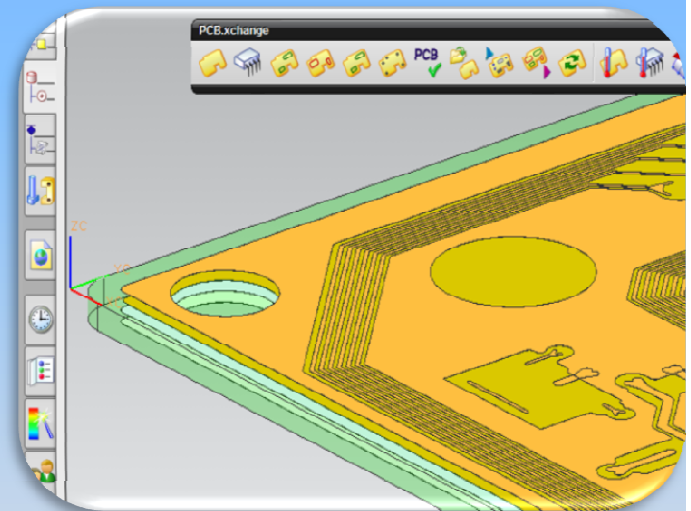
Internal Layer 2



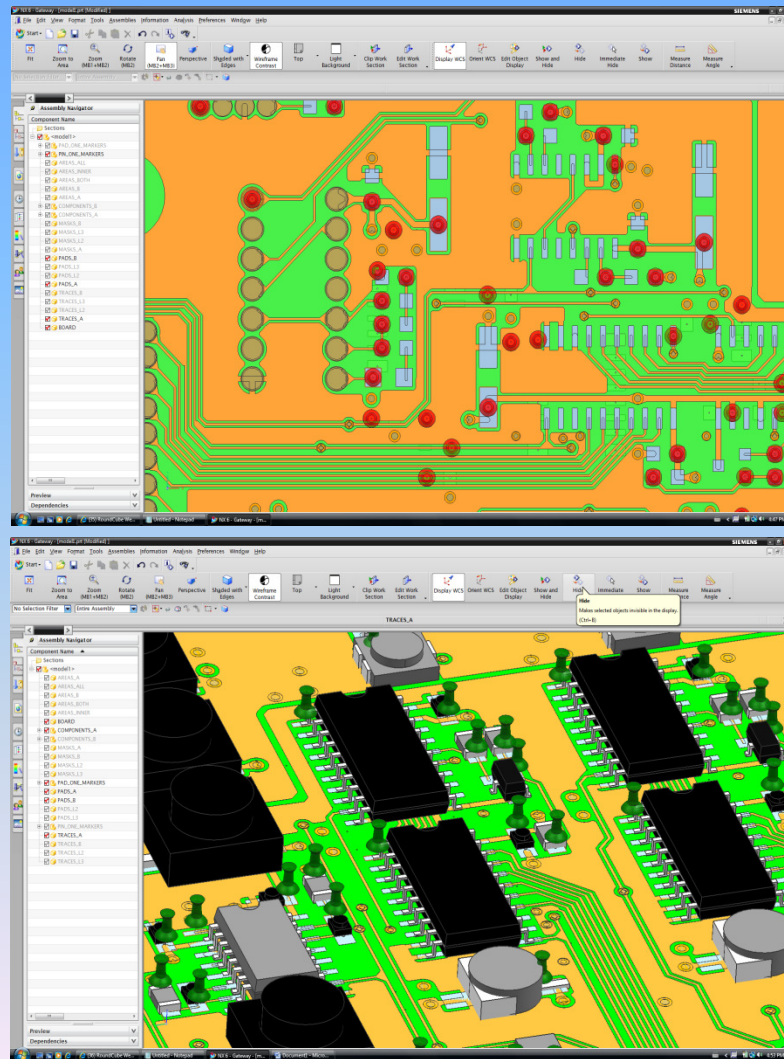
Bottom Layer



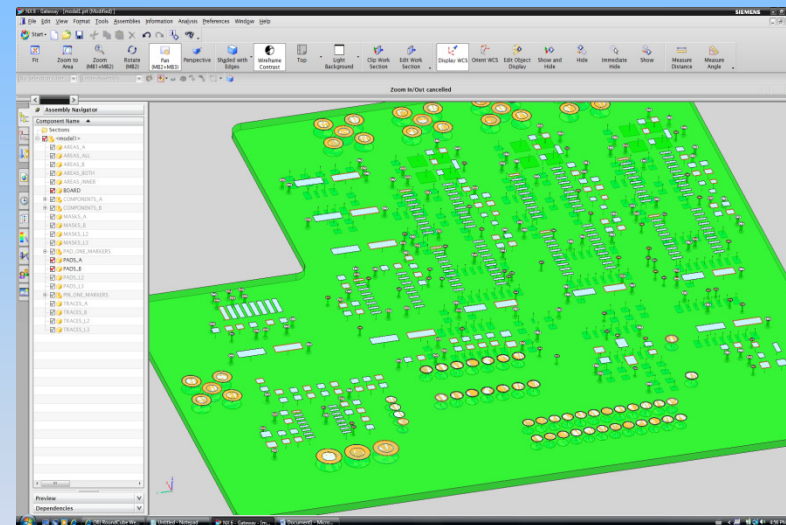
- Conductive Layers
- Option to import internal layers



More Electrical Data



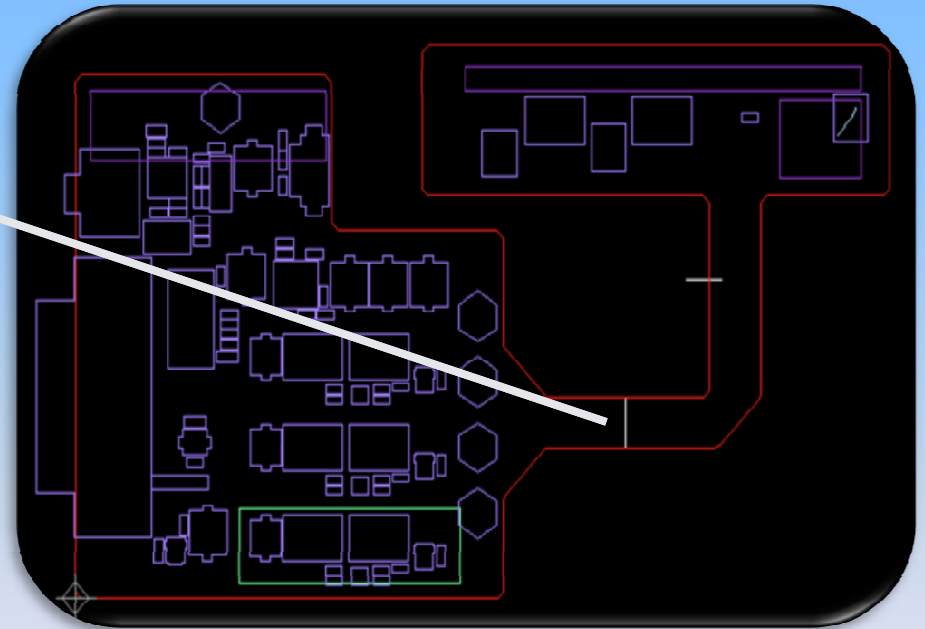
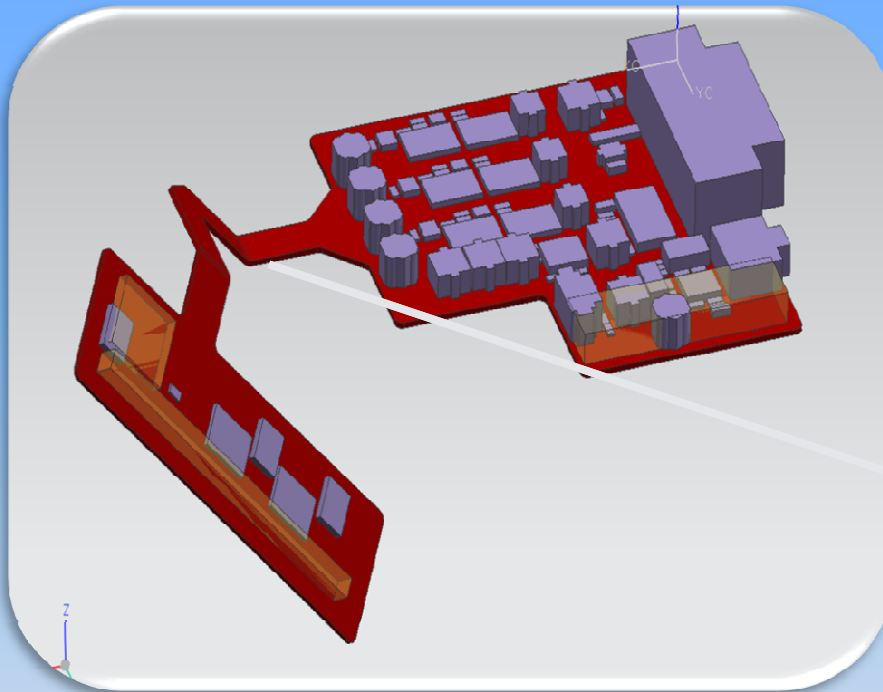
➤ Pin & Pad no1 information



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MAYA

More Mechanical Data



- ✓ Imports & exports bend information
- ✓ Automatically creates bend features and constraints components and areas to the board

Data Filtering

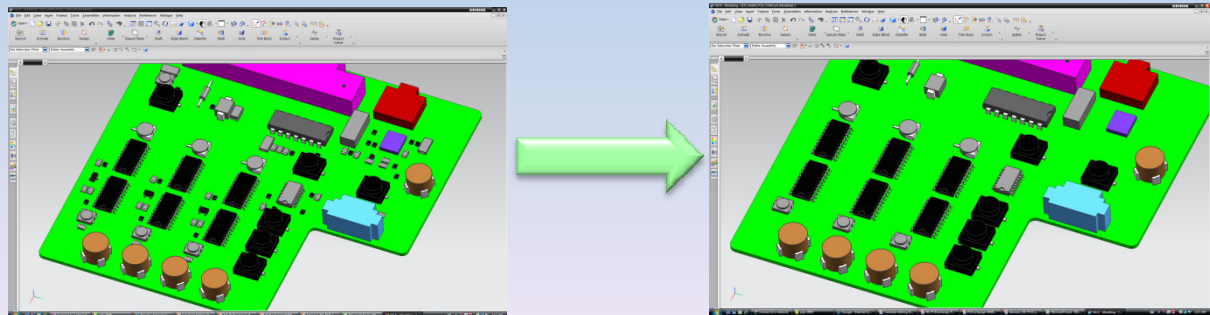
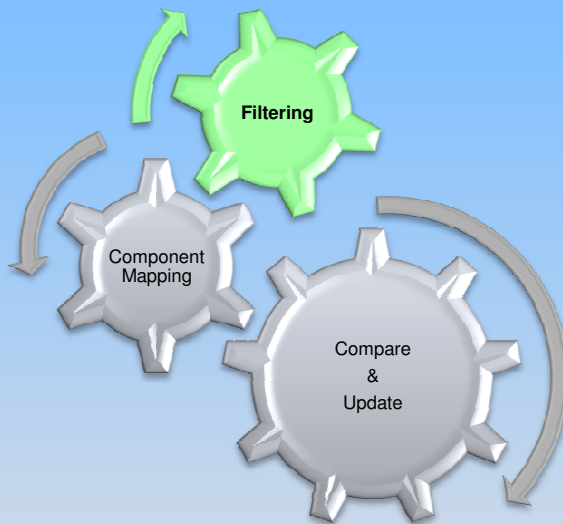
- ❑ You don't always want to exchange features and components

For example:

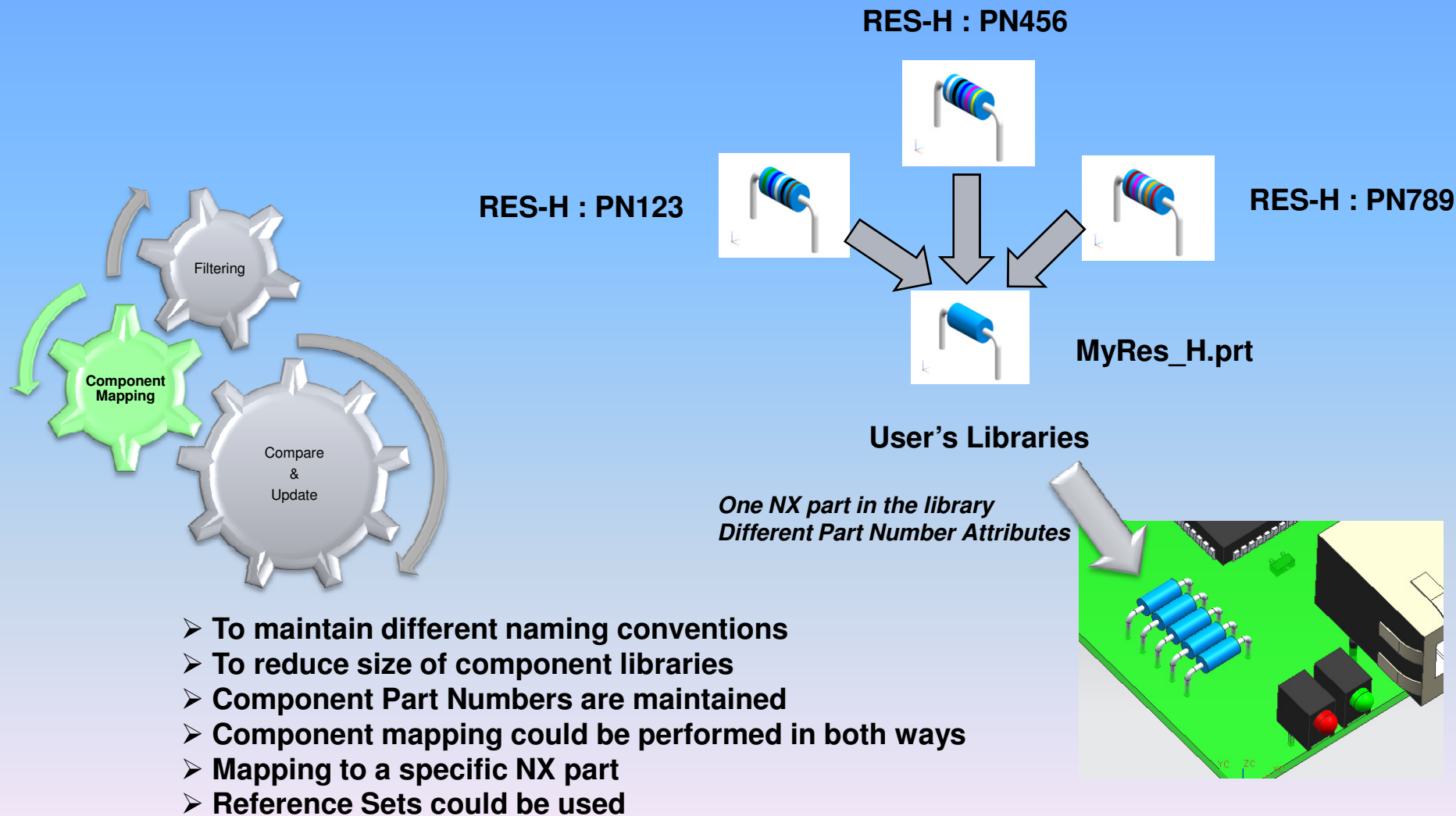
- Eliminate small pin holes
- Eliminate small surface mount components, (no impact on the mechanical layout)
- Eliminate passive components (do not generate heat)

- ❑ Filtering could be done when exporting or importing data

- ❑ Pre-defined and User-defined filter rules

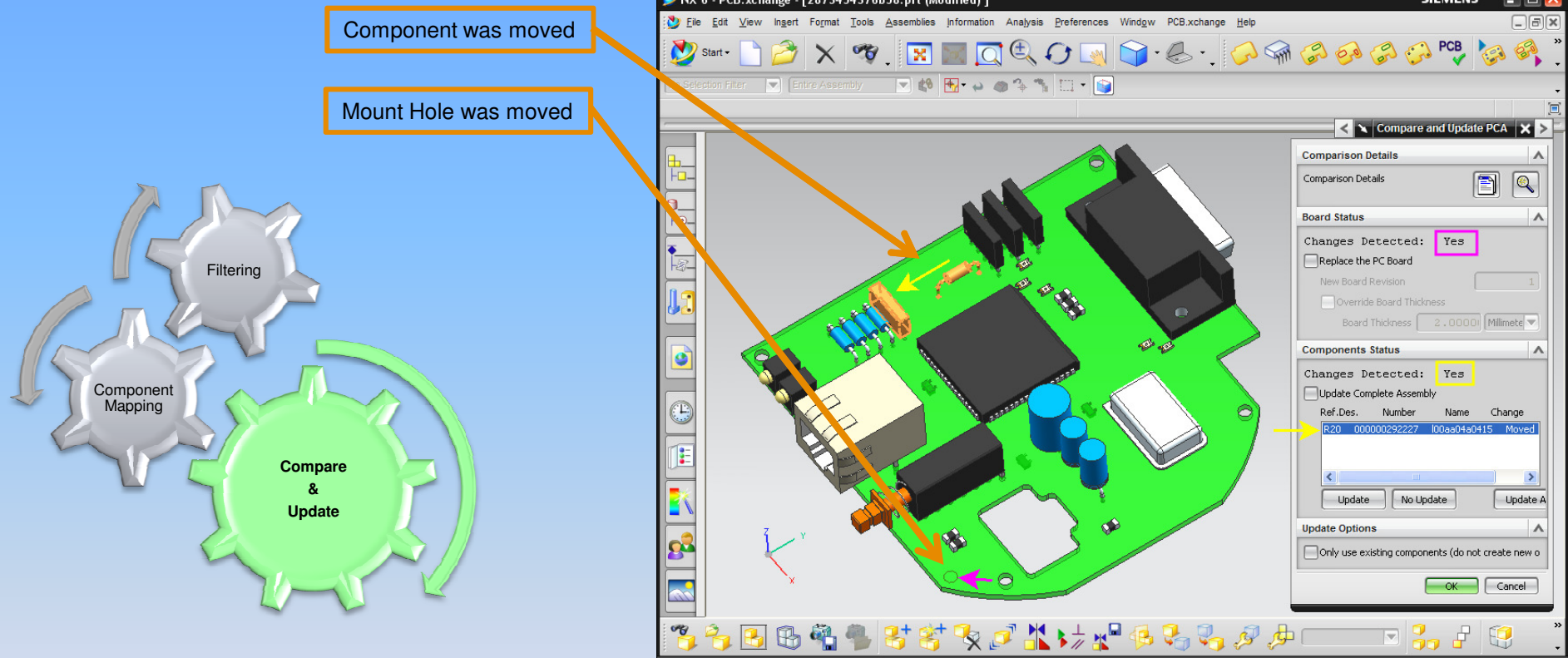


Component Mapping



- To maintain different naming conventions
- To reduce size of component libraries
- Component Part Numbers are maintained
- Component mapping could be performed in both ways
- Mapping to a specific NX part
- Reference Sets could be used

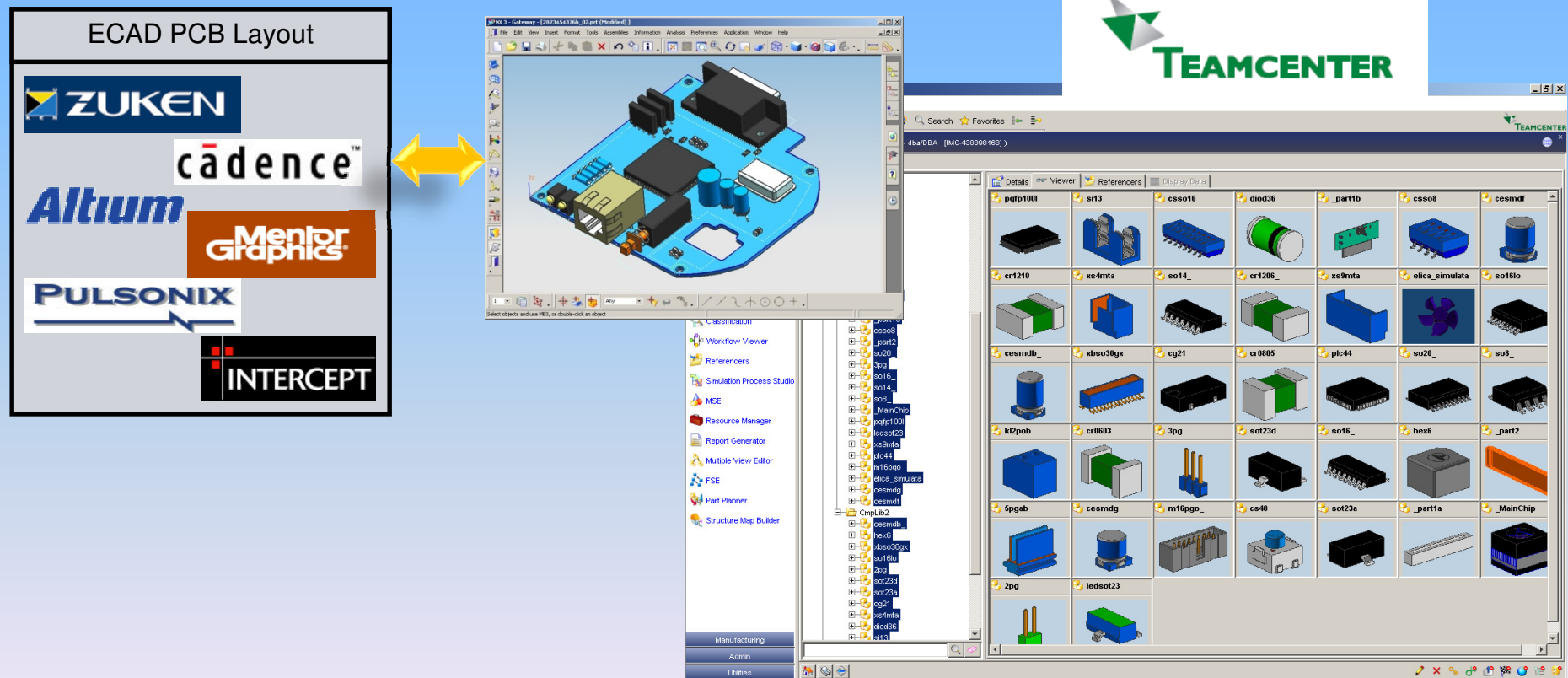
Compare & Update



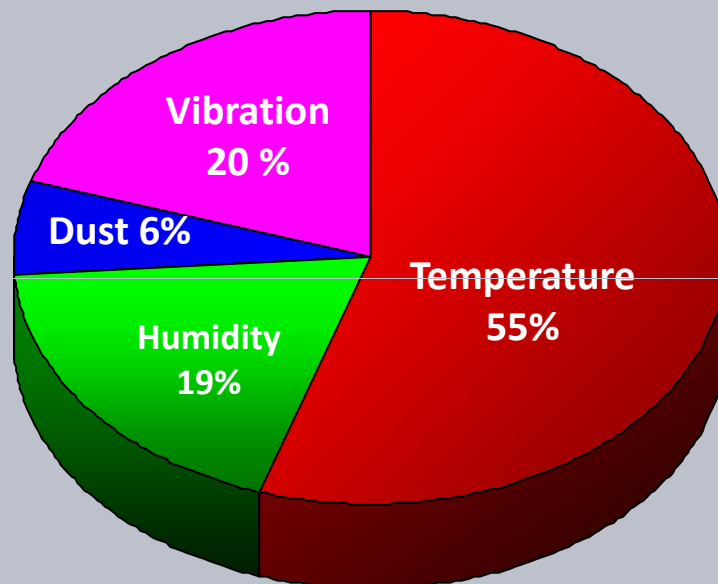
- ✓ Generates a detailed comparison report
- ✓ Provides graphical preview of changes
- ✓ Overlaps NX and ECAD Boards & Board Features
- ✓ Allows a selective update of the NX model

Data Management

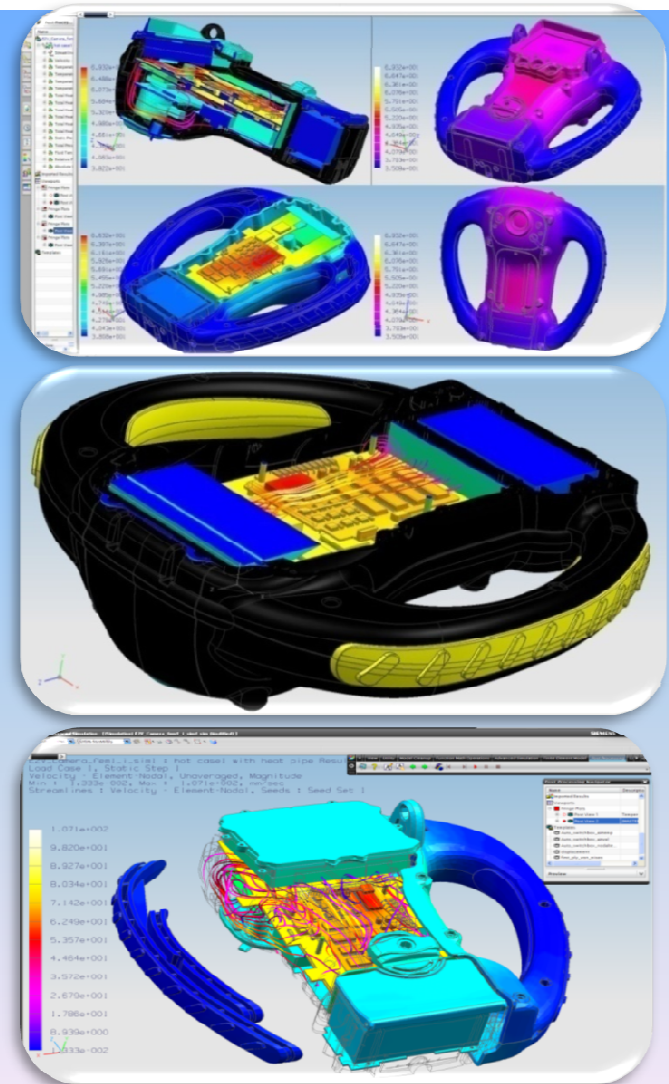
- Component parts found in Teamcenter database are automatically used
- New components are created from their ECAD footprints
- PC Assembly is created directly in Teamcenter Database



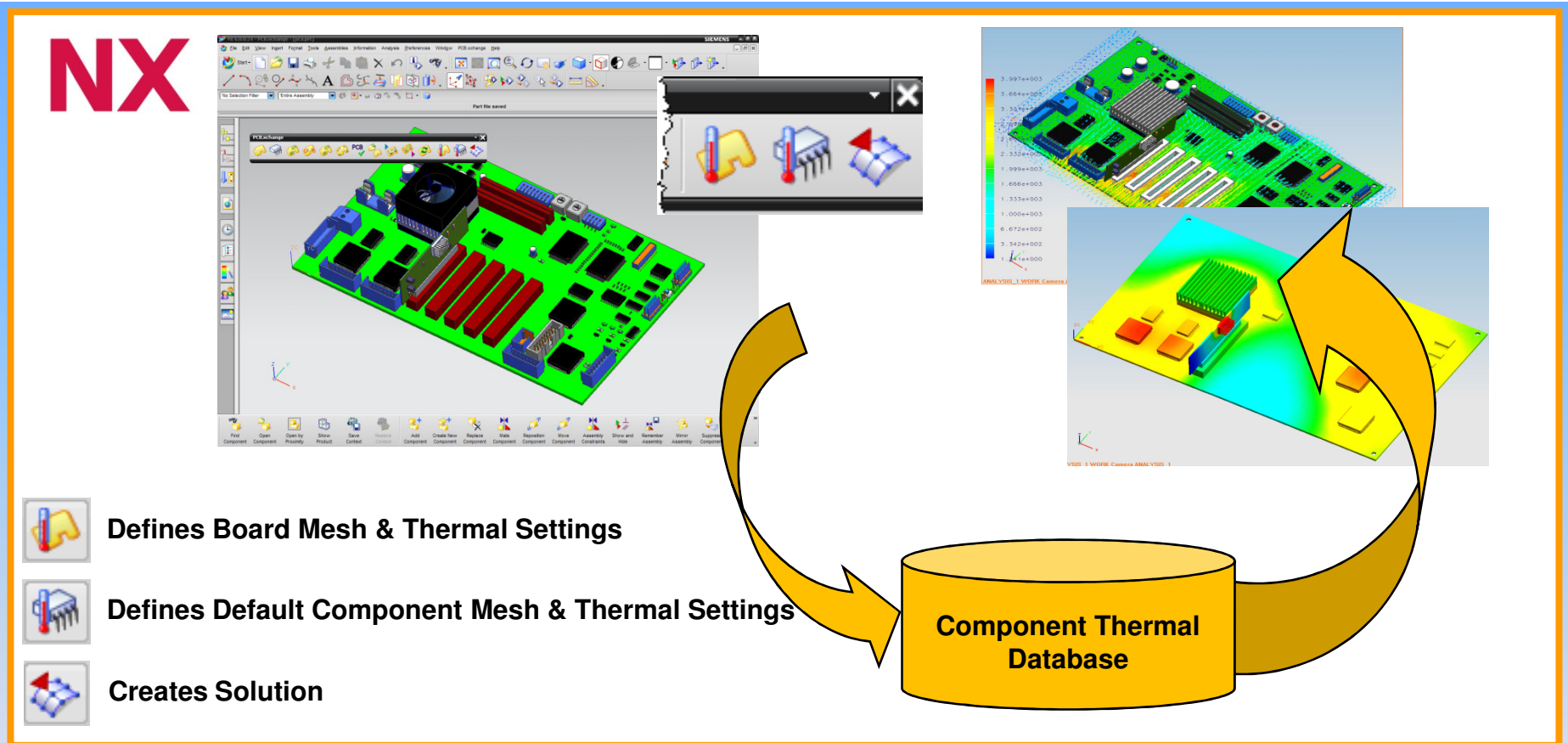
Major Causes of Electronic Failures



Source: US Air Force Avionics Integrity Program Report



Direct access to NX Thermal, NX Electronic Systems Cooling, NX Space Systems Thermal.



Automatically creates a ready-to-solve model:

- Creates the Fem and Sim.
- Meshes the Board & components
- Assigns Material and Physical Properties to the Board and Components Meshes
- Creates Heat Loads and Thermal Couplings



How do we turn untested product ideas into proven global innovations?

The Siemens answer: PLM Software for increased quality and 95 percent less rework.

Answers for industry.

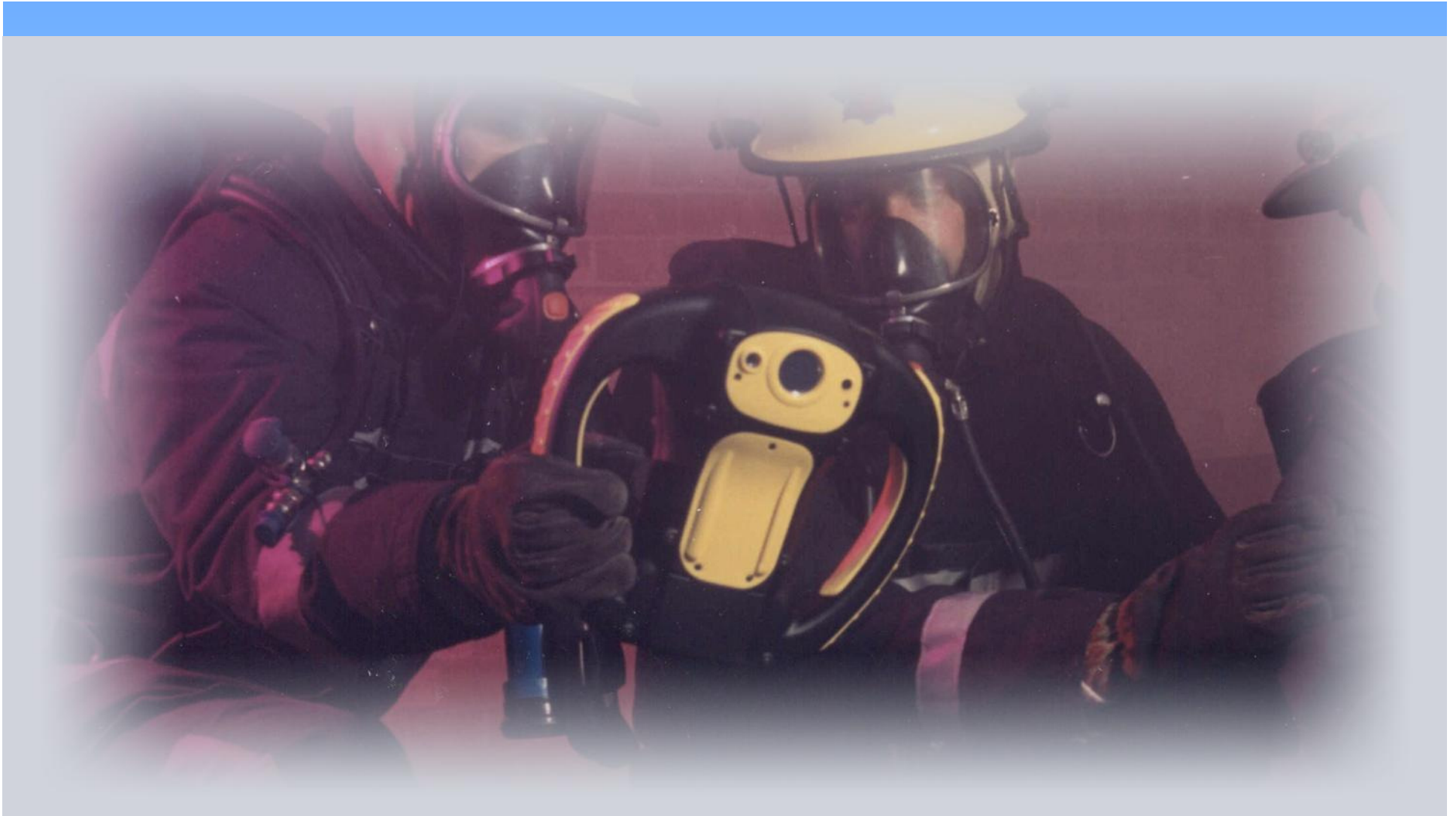
SIEMENS

NX / NX PCB.xchange demo.

Thermal Imaging Camera



Virtual and real come together...





Thank You